## What Is Claimed Is:

1. A device (10, 30) for the shakeproof accommodation of electrical special components (11, 12, 36, 38) and/or electrical circuits, in particular in the development as a second component set for a control unit, made up of

a carrier (13, 31) onto which a circuit substrate (14, 35) having the special components (11, 12, 36, 38) fastened onto it is mounted in an electrically insulated manner at least over a partial surface.

- 2. The device as recited in Claim 1, wherein an electrically insulating medium is provided between the carrier (13, 31) and the circuit substrate (14, 35).
- 3. The device as recited in one of the preceding claims, wherein the circuit substrate (14, 35) is fastened to the carrier (13, 31) by a preferably heat-dissipating adhesive, a laminated-on adhesive foil, screws, rivets or crimping.
- 4. The device as recited in one of the preceding claims, wherein the circuit substrate (14, 35) has a printed-circuit board, a flex foil, a ceramic or a wire harness.
- 5. The device as recited in one of the preceding claims, wherein the carrier (13, 31) has passages for contact pins that pass through.
- 6. The device as recited in one of the preceding claims, wherein the circuit substrate (14, 35) fastened to the carrier (13, 31) is able to be connected to a control unit using pins (20, 20')(40,40').
- 7. The device as recited in Claim 6, wherein the pins are developed as a pin strip (20, 20'), as SMD pins (40, 40'), punched bent parts or male pin connectors.
- 8. The device as recited in Claim 7, wherein a pin strip (20, 20') is situated on a tab (17, 17'), of the circuit substrate (14), which protrudes outwards over the carrier (13).

- The device as recited in Claim 7,
  wherein each pin strip is pressed into the circuit substrate.
- 10. The device as recited in Claim 7, wherein the SMD pins (40, 40') are soldered onto the circuit substrate (35) and extend downwards via lateral edges (41, 41') of the carrier (31) to connect to a main board.
- 11. The device as recited in one of Claims 1 through 5, wherein the circuit substrate fastened to the carrier is able to be connected to the control unit via a flex foil and a plug connection.
- 12. The device as recited in one of the preceding claims, wherein the carrier (13, 31) has screw openings (16, 34) for the passage of especially fastening screws that are able to be screwed into the floor of a control unit.
- 13. The device as recited in one of the preceding claims, wherein the carrier (13, 31) is made of cast aluminum.